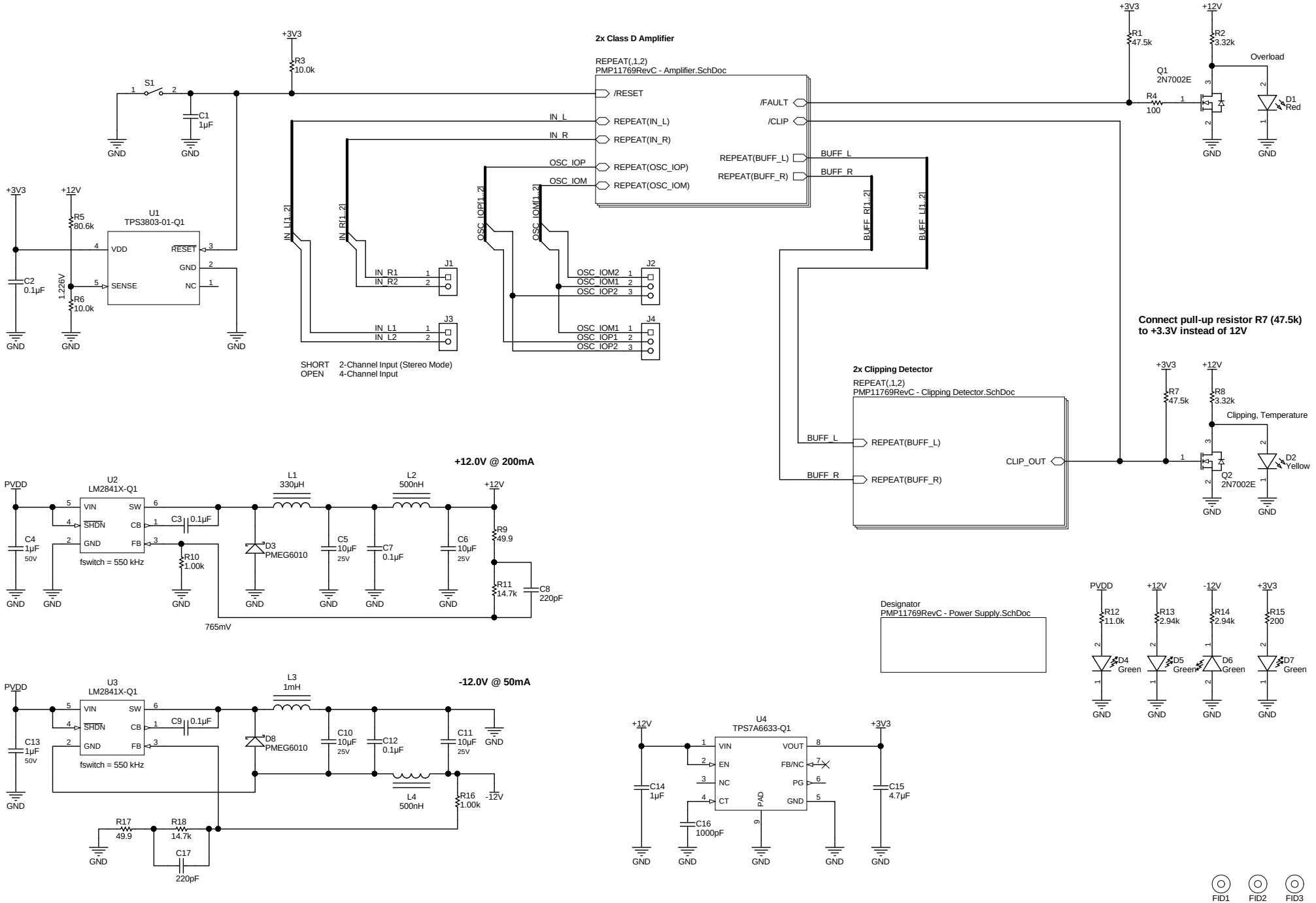

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TID #: TID		Project Title: Automotive Audio Amplifier	
Number: PMP11769	Rev: C	Sheet Title: System	
SVN Rev: Version control disabled		Assembly Variant: [No Variations]	Sheet: 1 of 4
Drawn By:Matthias Ulmann		File: PMP11769RevC - System.SchDoc	Size: A3
Engineer: Matthias Ulmann		Contact: http://www.ti.com/support	

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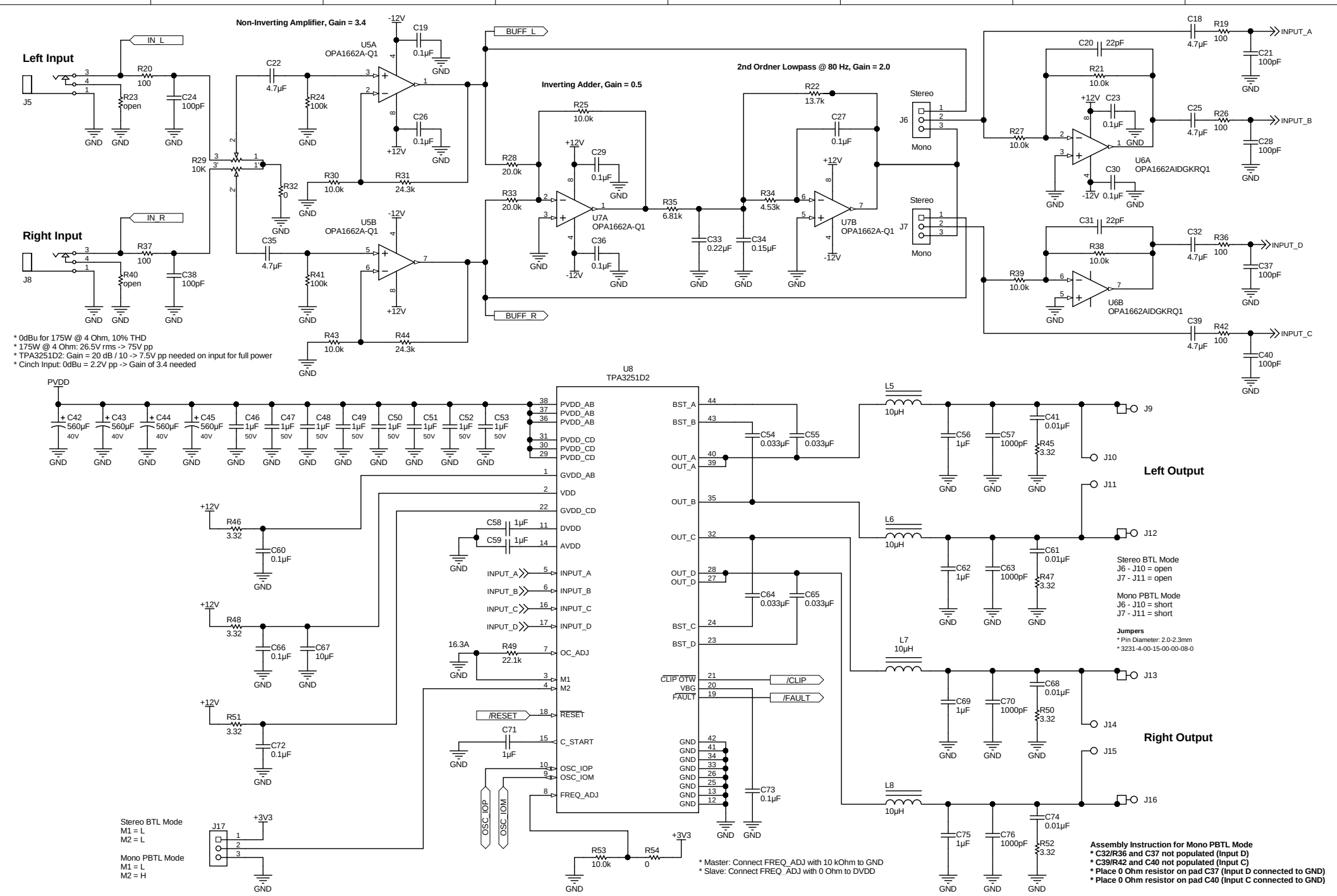

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TID #: TID	Project Title: Automotive Audio Amplifier	
Number: PMP11769 Rev: C	Sheet Title: Amplifier	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 4
Drawn By:Matthias Ulmann	File: PMP11769RevC - Amplifier.SchDoc	Size: A3
Engineer: Matthias Ulmann	Contact: http://www.ti.com/support	

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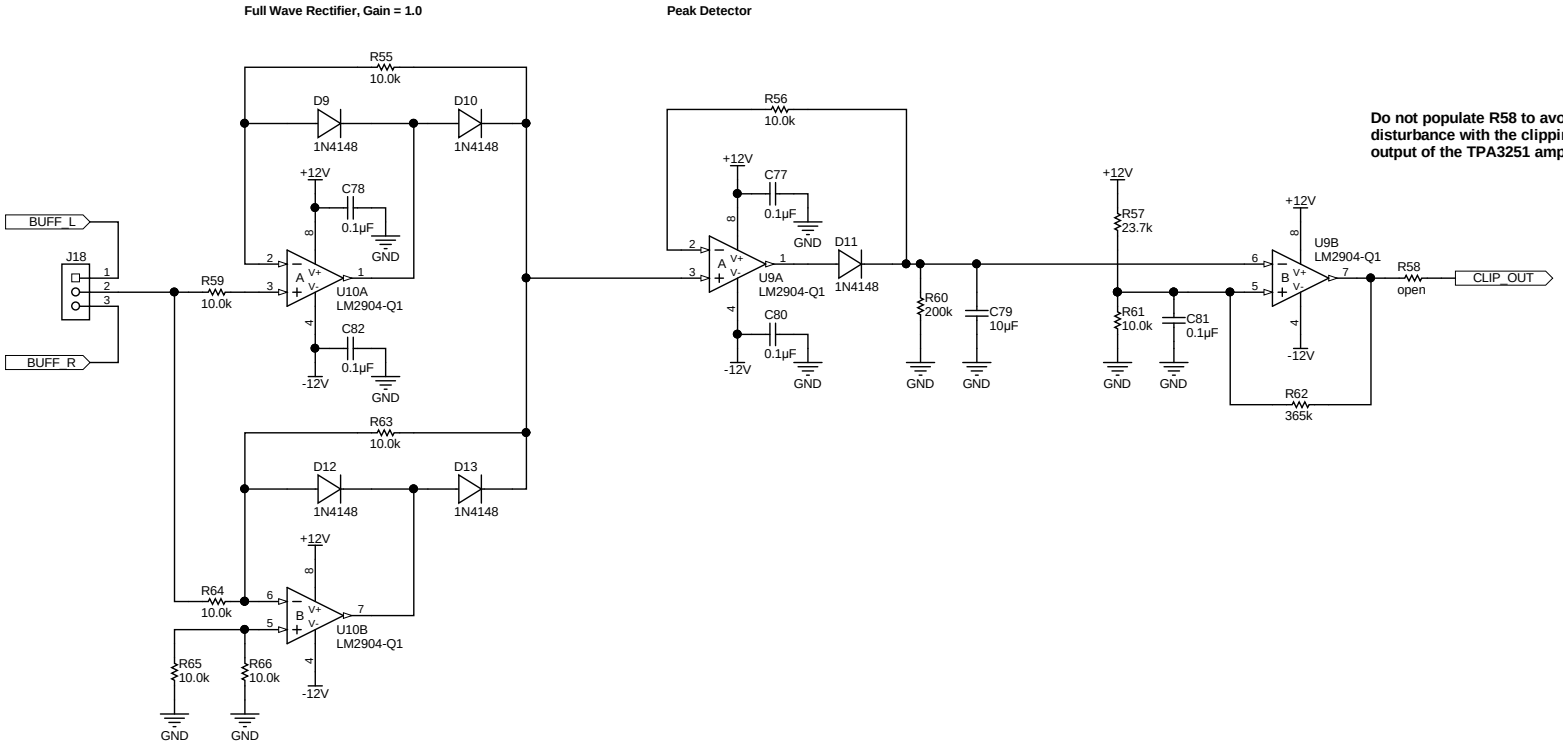

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Number: PMP11769 Rev: C	Sheet Title: Clipping Detector	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By:Matthias Ulmann	File: PMP11769Revc - Clipping Detector.SchDoc	Size: A3
Engineer: Matthias Ulmann	Contact: http://www.ti.com/support	

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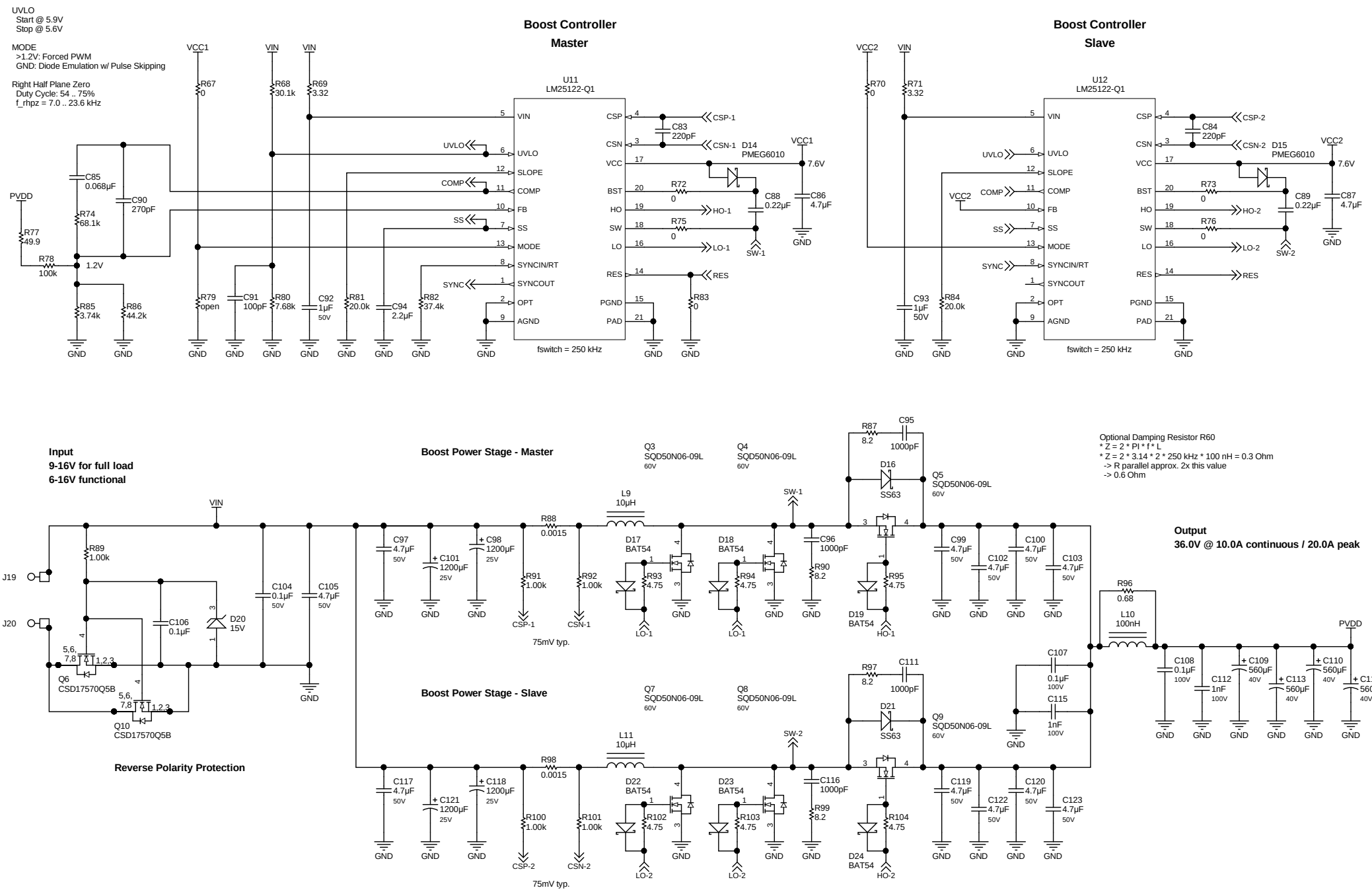

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TID #: TID		Project Title: Automotive Audio Amplifier	
Number: PMP11769	Rev: C	Sheet Title: Power Supply	
SVN Rev: Version control disabled		Assembly Variant: [No Variations]	Sheet: 4 of 4
Drawn By:Matthias Ulmann		File: PMP11769RevC - Power Supply.SchDoc	Size: A3
Engineer: Matthias Ulmann		Contact: http://www.ti.com/support	http://www.ti.com

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